DE 7 + T 3 PR W]€F , G S $@ PT 1p À 3 + UÀ PTÀS S PS 3 3 S 6 R P

Isolation Voltage	V_{iso}	3750	Vrms
Operating Temperature	T_{opr}	-55~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-55~125	
Soldering Temperature	T_{sol}	260	
Peak pulse voltage (T_j=25 ; non-repetitive,off-state)	V_{pp}	1	kV

NOTE1: μ

NOTE2:

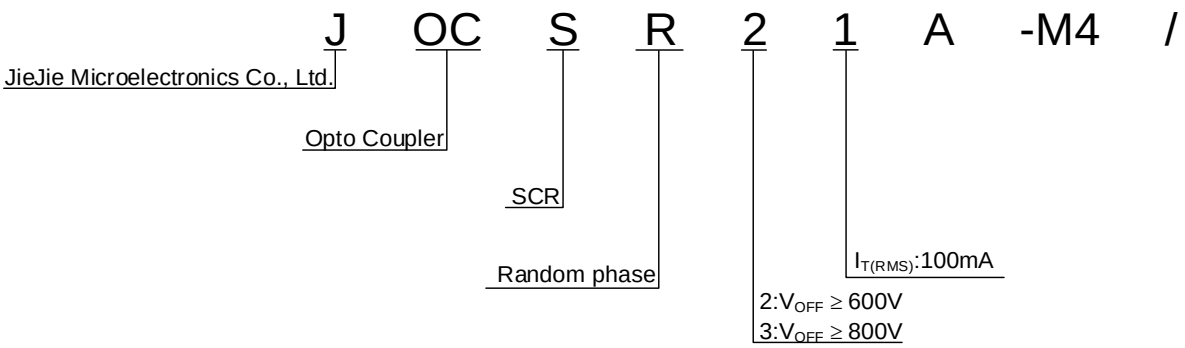
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter			Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage		V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current		I_R	V_R=6V	-	-	1	μA
	Input Capacitance		C_{in}	V=0, f=1kHz	-	14	-	pF
Output	Peak Off-state Current, Either Direction		I_{OFF}	V_{OFF}=Rated V_{OFF} I_F=0	-	-	100	nA
	Peak On-state Voltage, Either Direction		V_{TM}	I_{TM}=100mA	-	2	2.5	V
	Critical Rate of Rise of Off-state voltage		dV/dt	V_{PEAK}= Rated V_{PEAK} I_F=0	2000	-	-	V/μs
Transfer Characteristics	LED Trigger Current	JOCSR21A JOCSR31A	I_{FT}	Terminal Voltage=3V I_{TM}=100mA	-	-	10	mA
		JOCSR21B JOCSR31B			-	-	5	
		JOCSR21C JOCSR31C			-	-	3	
	Holding Current		I_H	I_{TM}=2mA, I_F=Rated I_{FT}	-	500	-	μA
	Isolation Resistance		R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	Ω
	Floating Capacitance		C_{IO}	V=0, f=1MHz	-	5	-	pF
	Response Time		t_{on}	V_D=6V, R_L=100Ω, I_F=20mA	-	15	50	μs

NOTE3:

NOTE4:

ORDERING INFORMATION



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

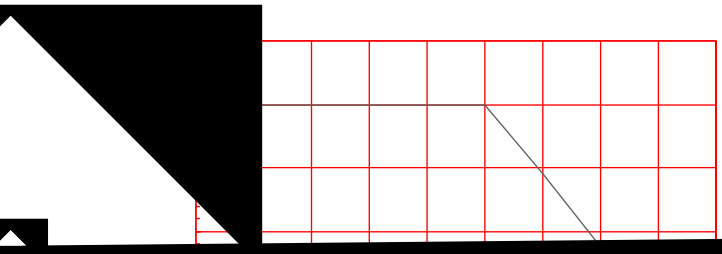
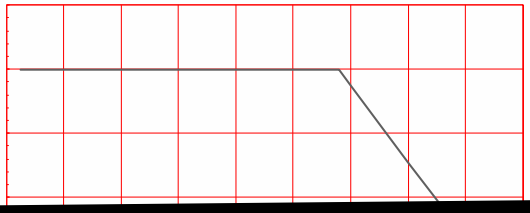


FIG.2: On-state Terminal Current vs. Ambient Temperature



TEST CIRCUITS

FIG.12: Test Circuits of Turn On Time

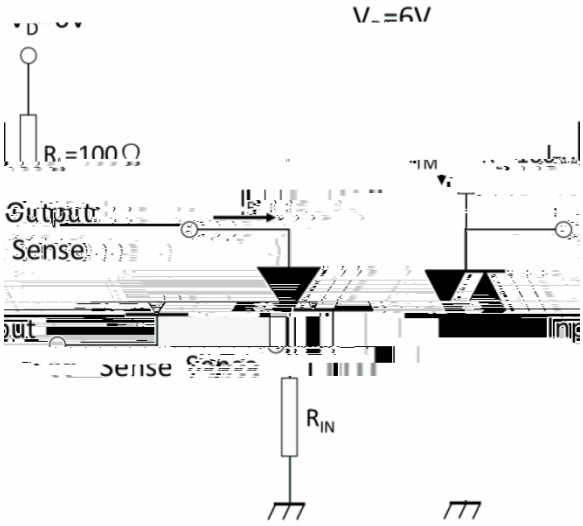


FIG.13: Waveforms of Turn On Time

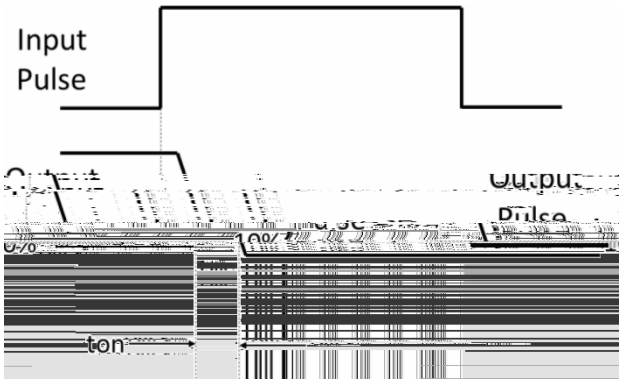


Fig.14: Test Circuits of dV/dt

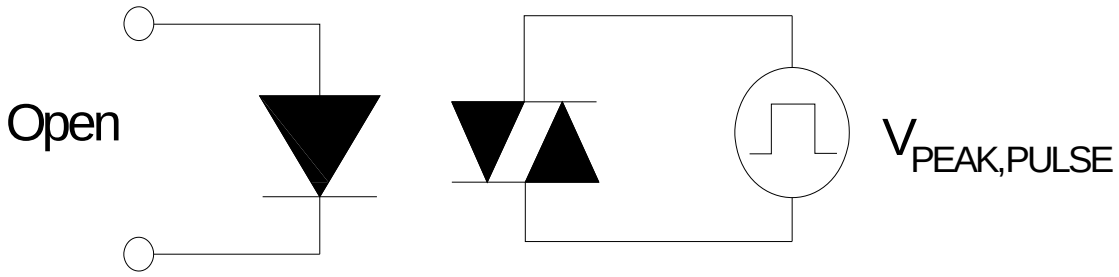
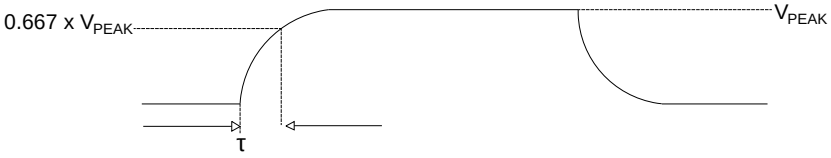
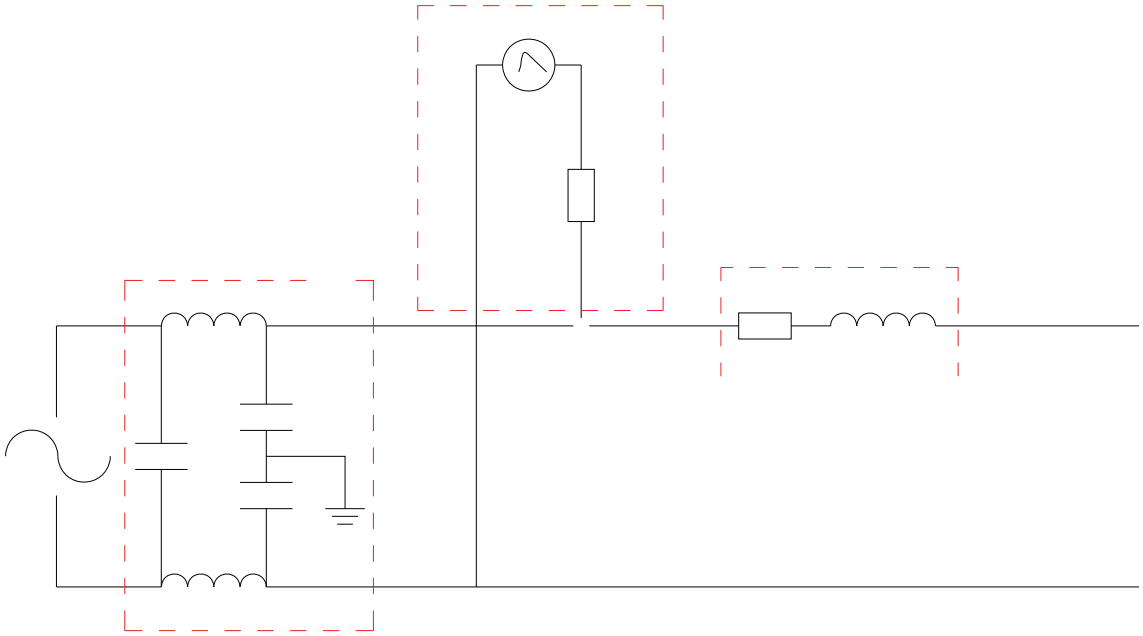


Fig.15: Waveforms of dV/dt

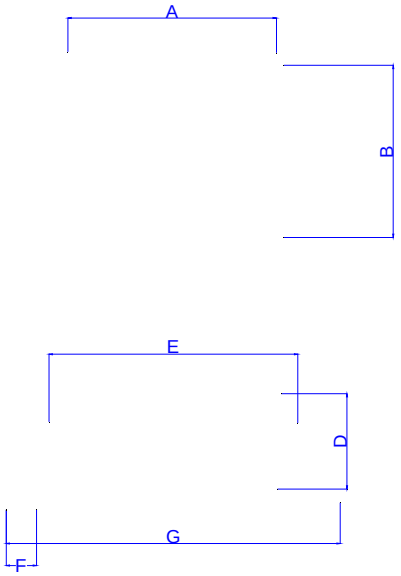


$$dV/dt = \frac{0.667 \times V_{PEAK}}{\tau}$$

FIG.16: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



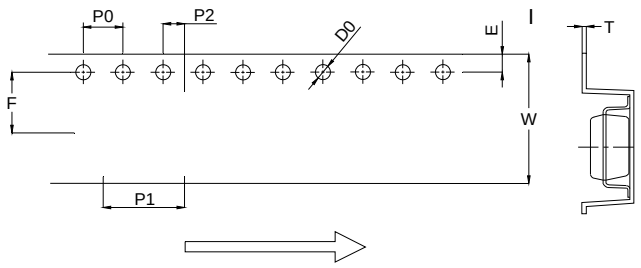
Package Dimension (Unit: mm)



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C						
E						
G	6.70			0.264C φ Ḥ		i è 4 ˜ Ŏ Ŭ
I						

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None



Dimensions			
Ref.	Millimeters		Inches
0.154	4.10	8.10	0.902.10
0.083	4.40		

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1